Title (en)
MULTI-MILLING METHOD FOR THE PRODUCTION OF PRINTED CIRCUITS AND THE PRINTED CIRCUITS THUS OBTAINED

Title (de)
MEHRFACHBEARBEITUNGSVERFAHREN ZUR HERSTELLUNG GEDRUCKTER SCHALTUNGEN UND SOMIT ERHALTENE GEDRUCKTE SCHALTUNGEN

Title (fr)
PROCEDE DE FRAISAGE MULTIPLE POUR LA FABRICATION DE CIRCUITS IMPRIMES ET CIRCUIT IMPRIME AINSI OBTENU

Publication
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Application
EP 02796283 A 20020821

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Abstract (en)
A multiple-milling process for manufacturing printed circuits and the printed circuit thus obtained, constituted by a process for preparing the substrate of the printed circuit boards (1) for the production of bending areas (2) from whence to bend said printed circuits (1). This process consists of a multiple-milling system, by means of a mill (3) with special features, comprising a roll provided with multiple polishing strips on its surface, capable of making an undercutting in parallel strips (4) in said bending areas (2) of a printed circuit (1), allowing for their subsequent bending without deteriorating the metallic material conductive tracks adhered to the printed board's substrate on the side opposite the milled surface. <IMAGE>

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